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LEDs**
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SHEET 3

FMC CONN
SHEET 4

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POWER SEQUENCER
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POWER SUPPLIES
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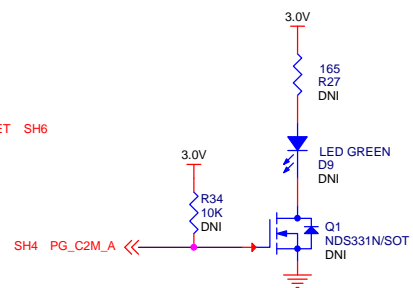
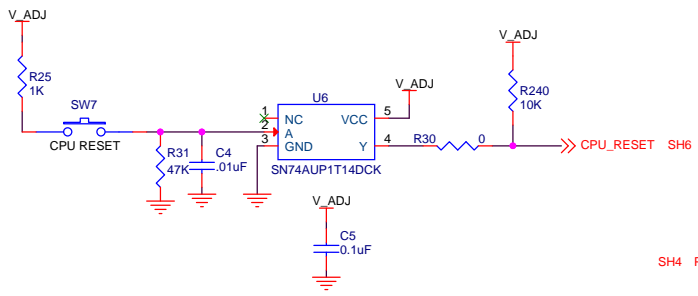
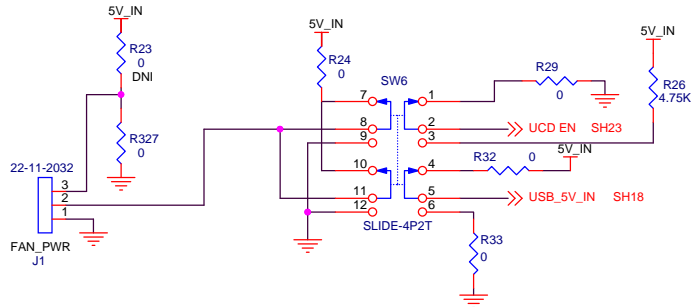
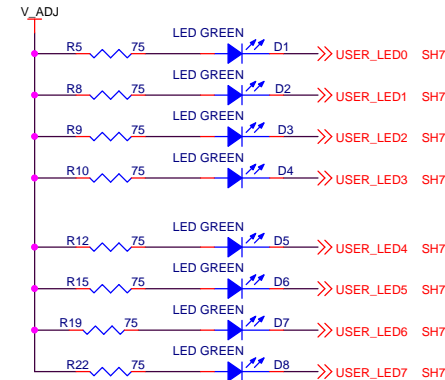
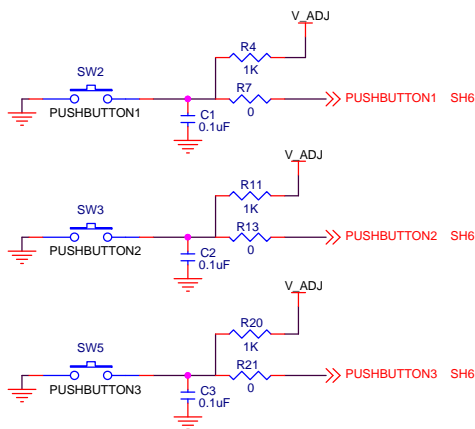
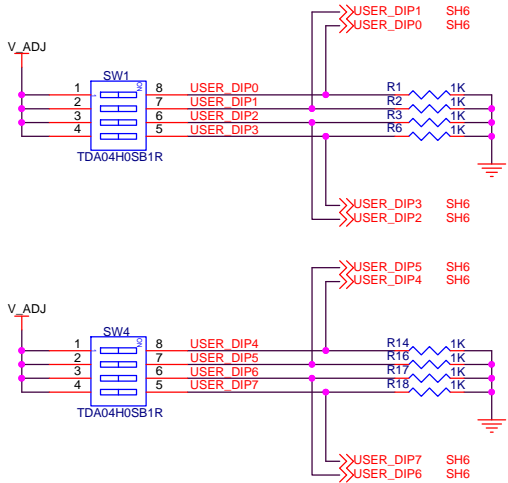
NOTE: DNI = DO NOT INSTALL COMPONENT.

 **TEXAS INSTRUMENTS**

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Drawn: L. NGUYEN	Size: B	Document Number	Rev: B
Engineer: J. SETON / E. DWOBENC	Date: Thursday, August 15, 2013	Sheet 1 of 23	

Buttons, Switches, LEDs

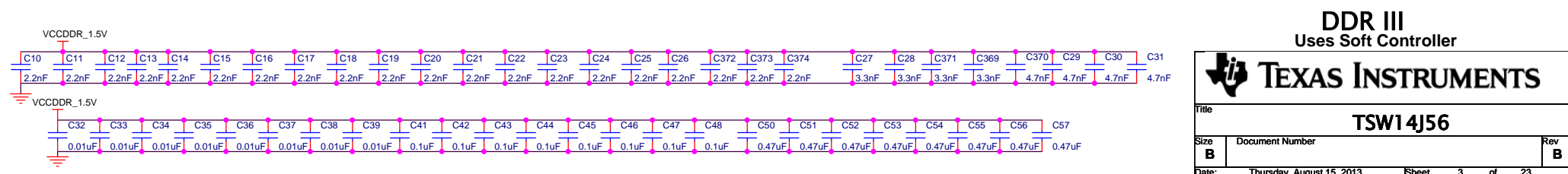
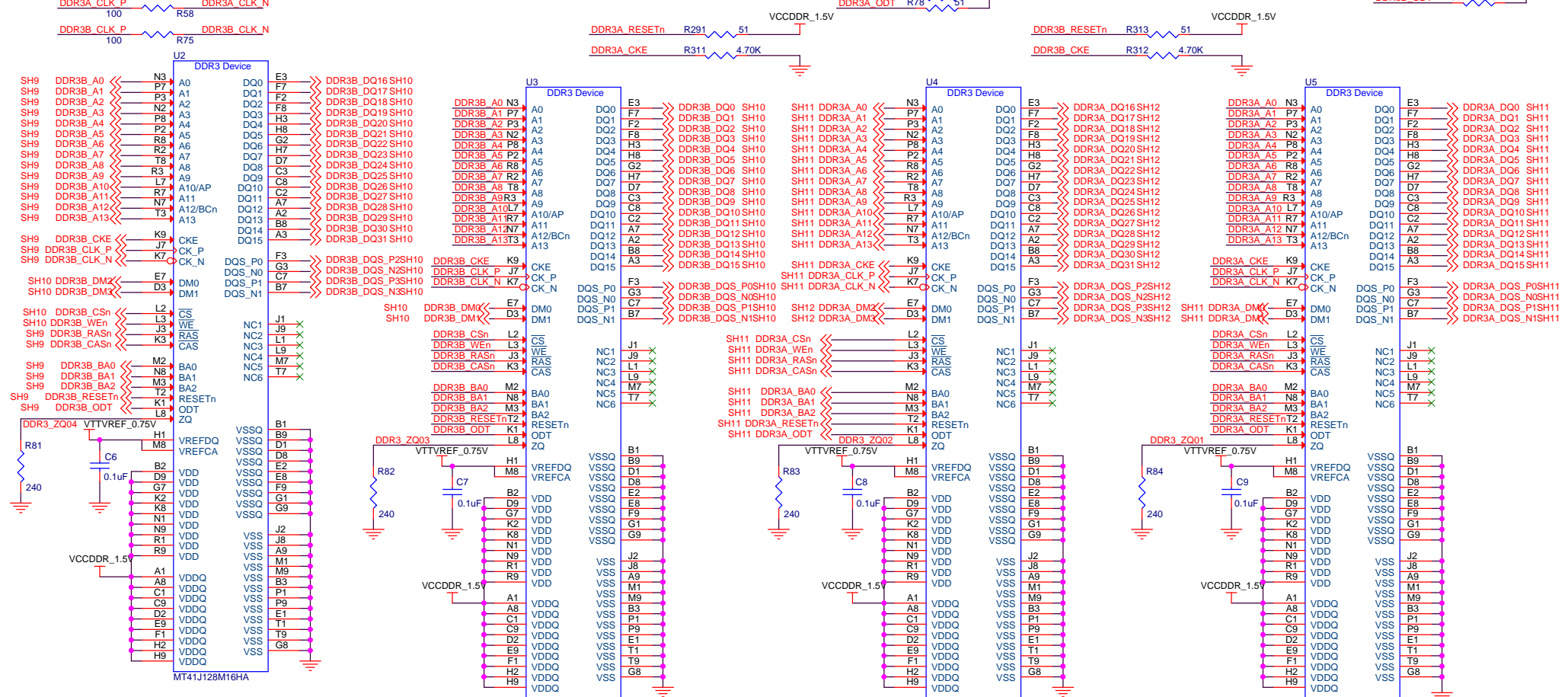
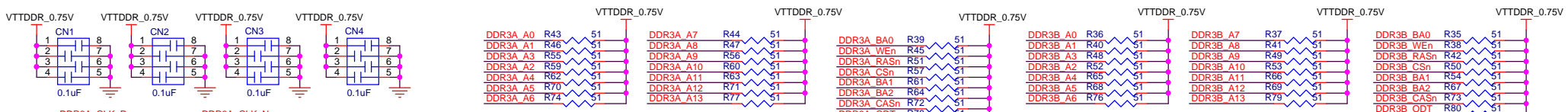


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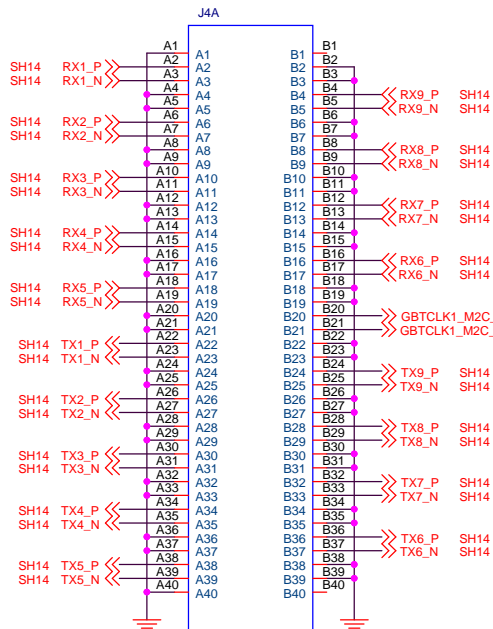
DDR III
Uses Soft Controller

TEXAS INSTRUMENTS

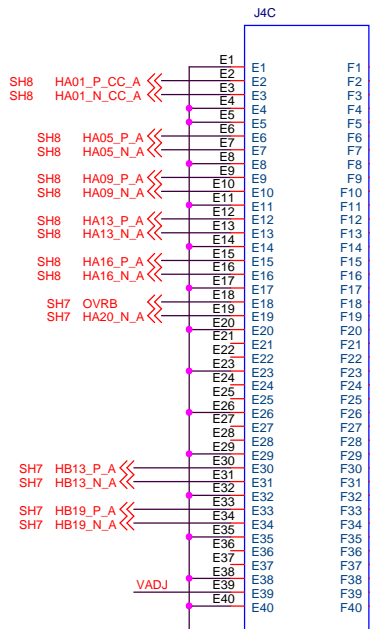
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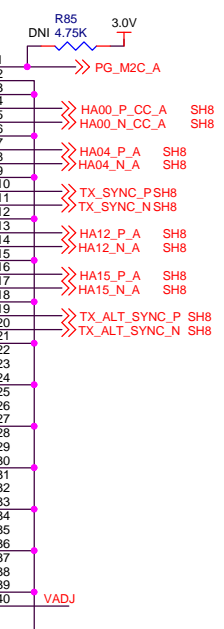
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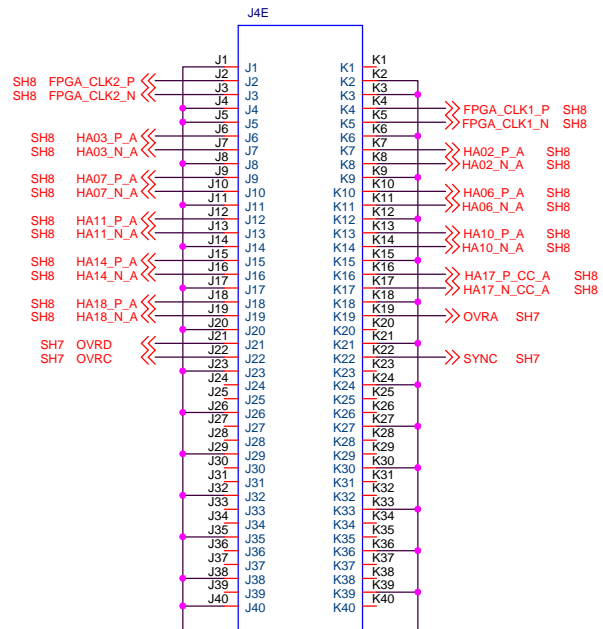
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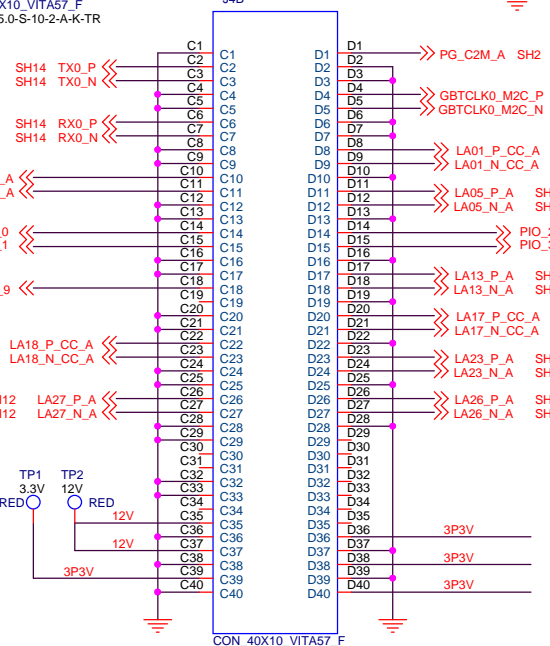
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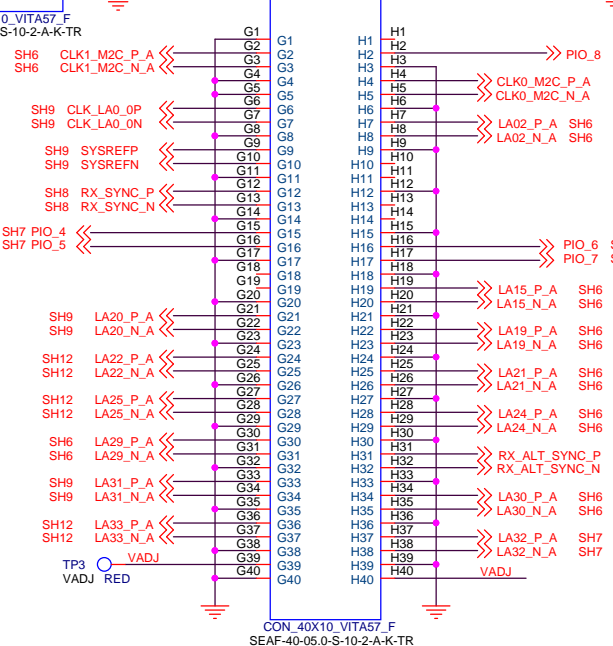
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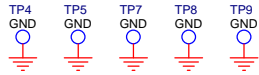
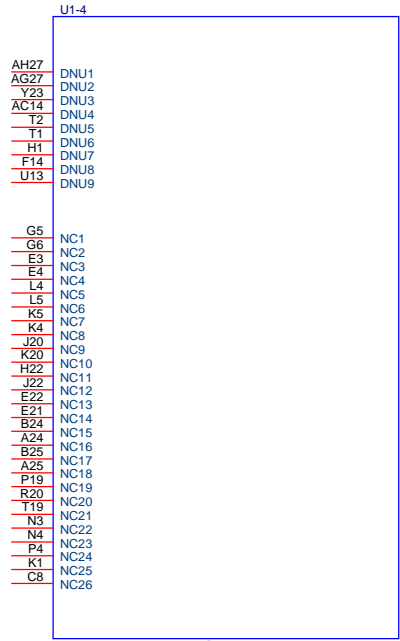
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FPGA=CARRIER
DUT=MEZ
M2C - ADC
C2M - DAC

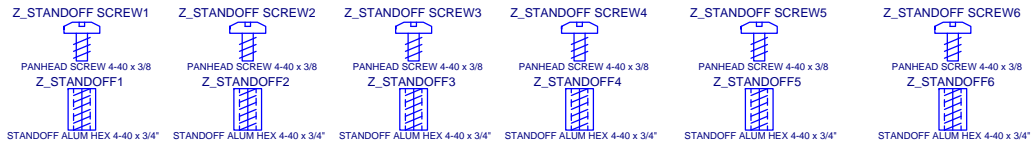
FMC HPC CONNECTOR




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MECHANICAL PARTS



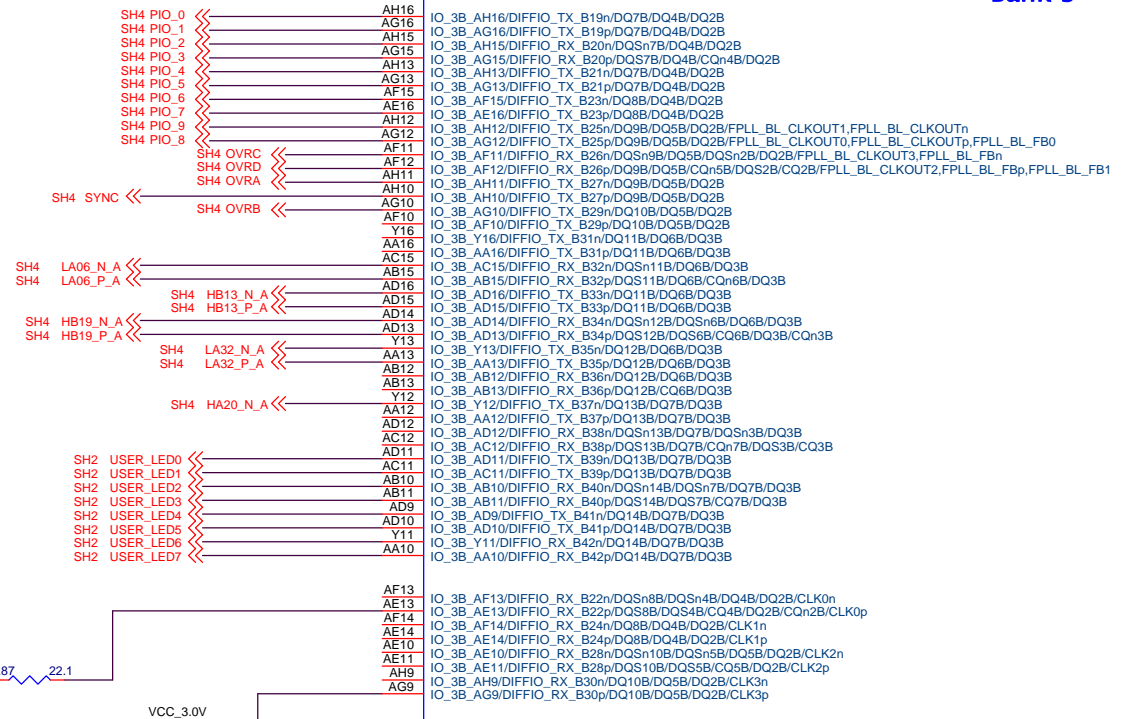
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U1-3

Bank 3

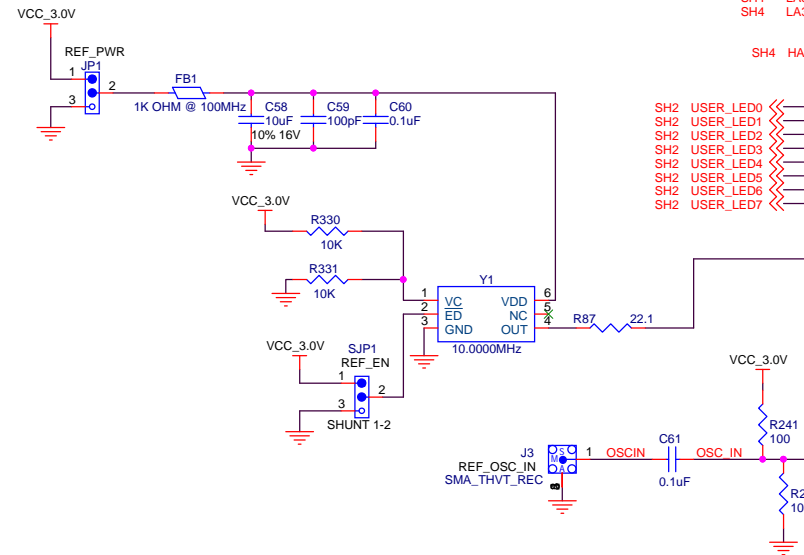


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BANK 3



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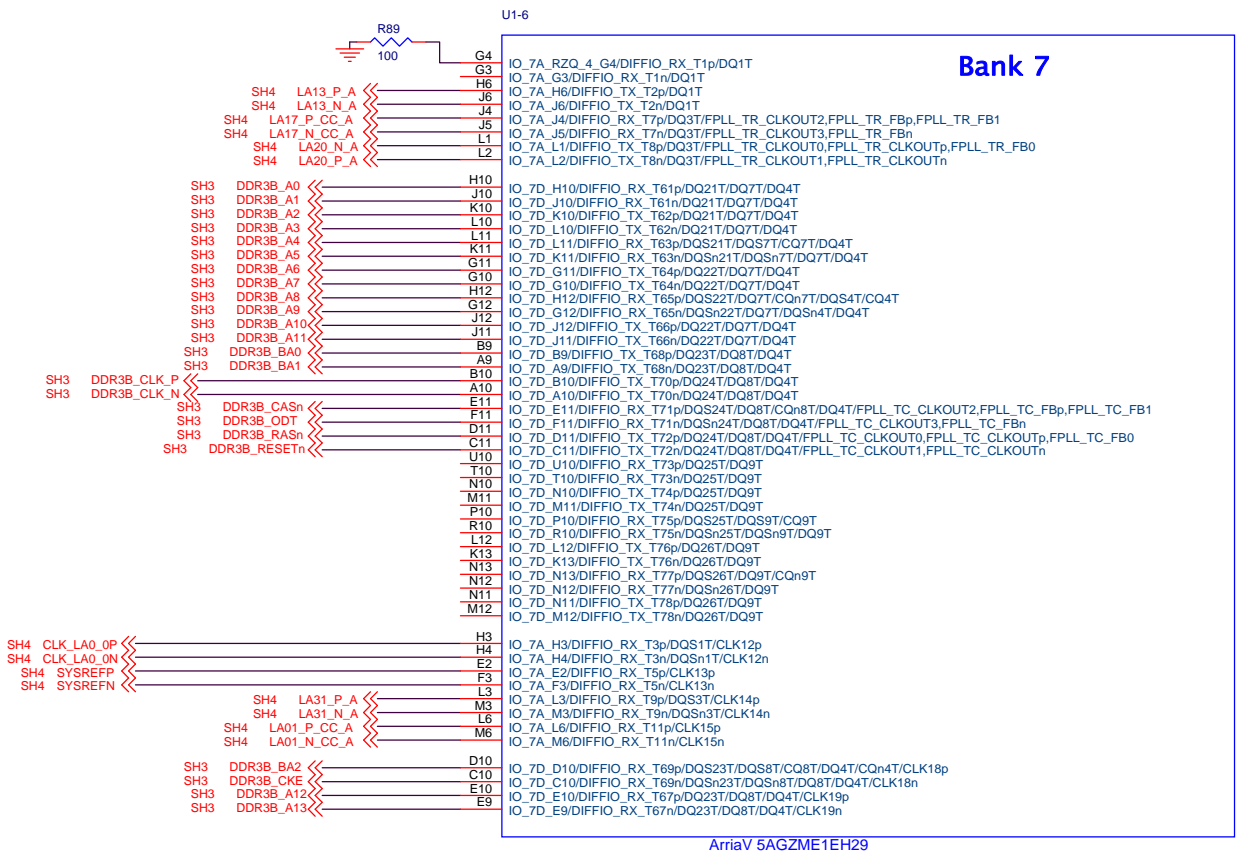
FPGA Bank 4

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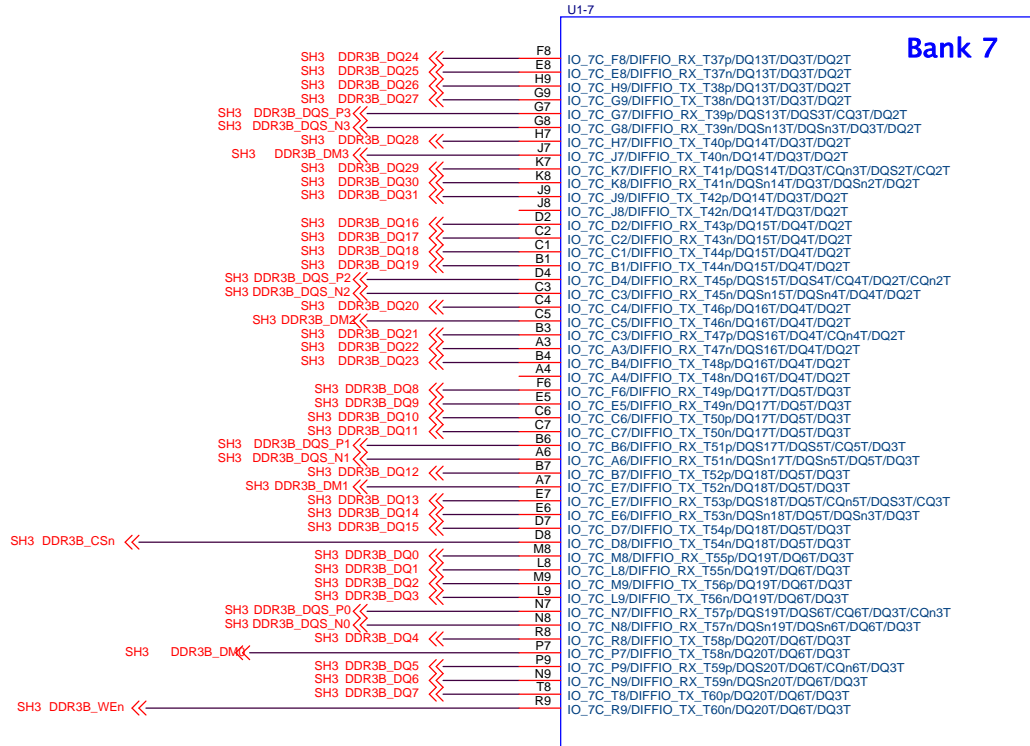
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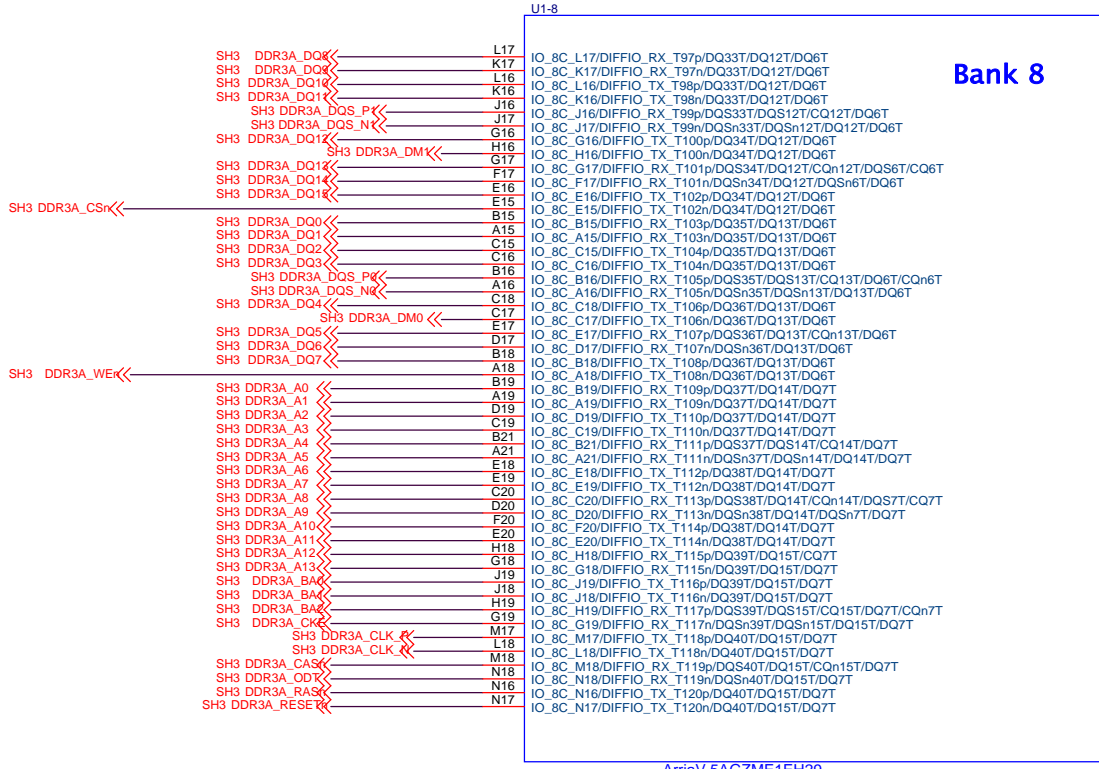
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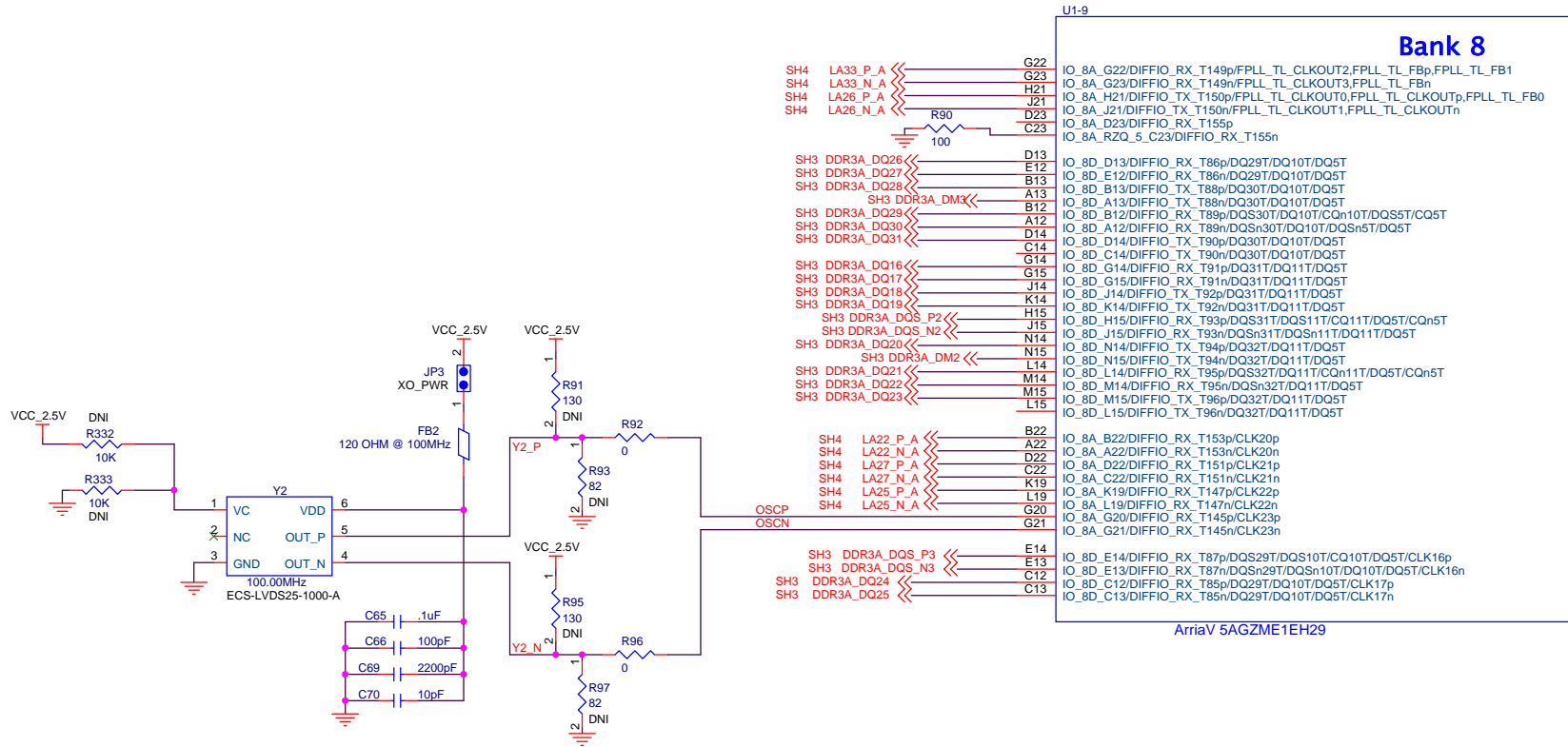
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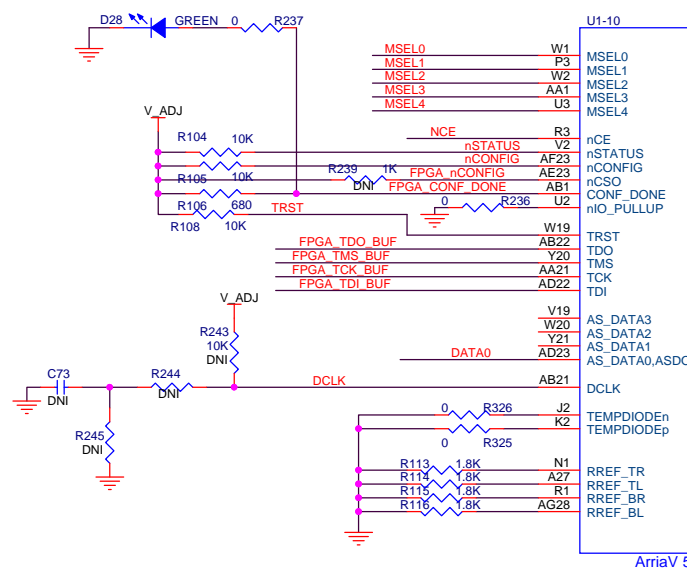
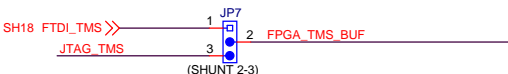
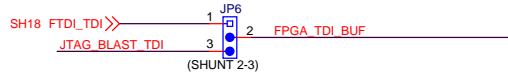
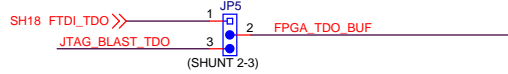
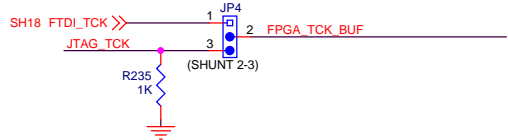
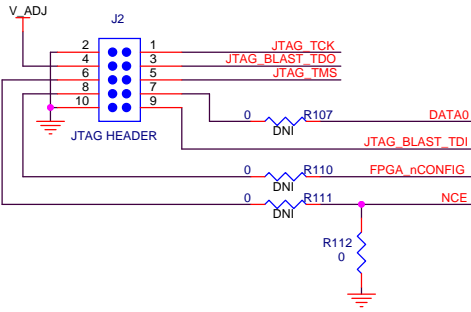
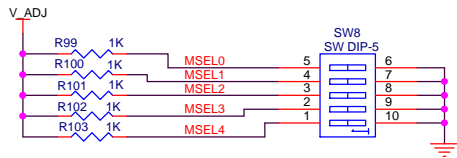
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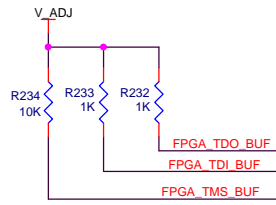
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MSEL0	W1	MSEL0
MSEL1	P3	MSEL1
MSEL2	W2	MSEL2
MSEL3	AA1	MSEL3
MSEL4	U3	MSEL4
nCE	R3	nCE
nSTATUS	V2	nSTATUS
nCONFIG	AF23	nCONFIG
FPGA_nCONFIG	AE23	nCONFIG
FPGA_CONF_DONE	AB1	nCSO
TRST	U2	CONF_DONE
FPGA_TDO_BUF	W19	nIO_PULLUP
FPGA_TMS_BUF	AB22	TRST
FPGA_TCK_BUF	Y20	TDO
FPGA_TDI_BUF	AA21	TMS
	AD22	TCK
		TDI
	V19	AS_DATA3
	W20	AS_DATA2
	Y21	AS_DATA1
	AD23	AS_DATA0,ASDO
	AB21	DCLK
	J2	TEMPDIODEn
	K2	TEMPDIODEp
	N1	RREF_TR
	A27	RREF_TL
	R1	RREF_BR
	AG28	RREF_BL

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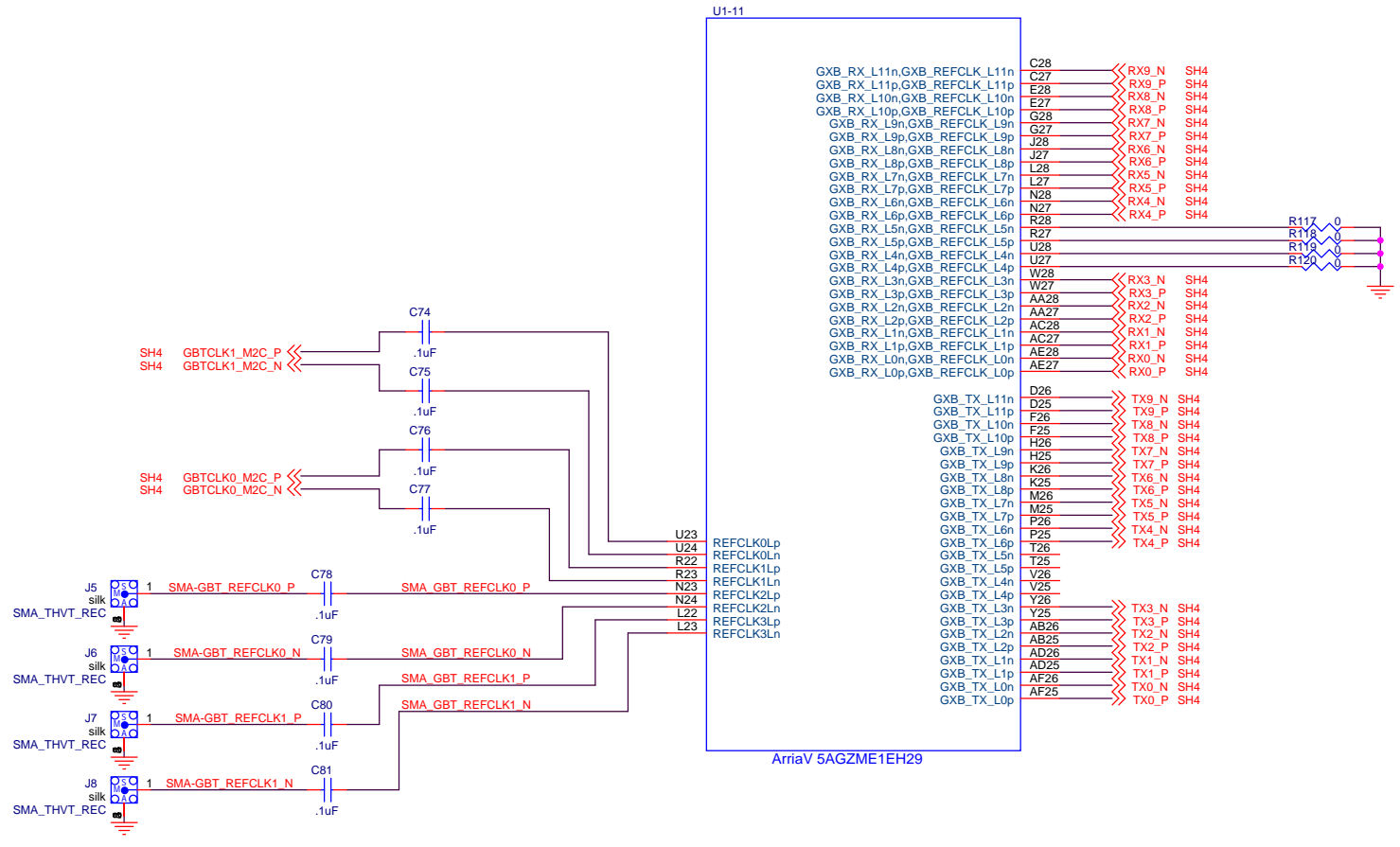
FPGA CONFIGURATION

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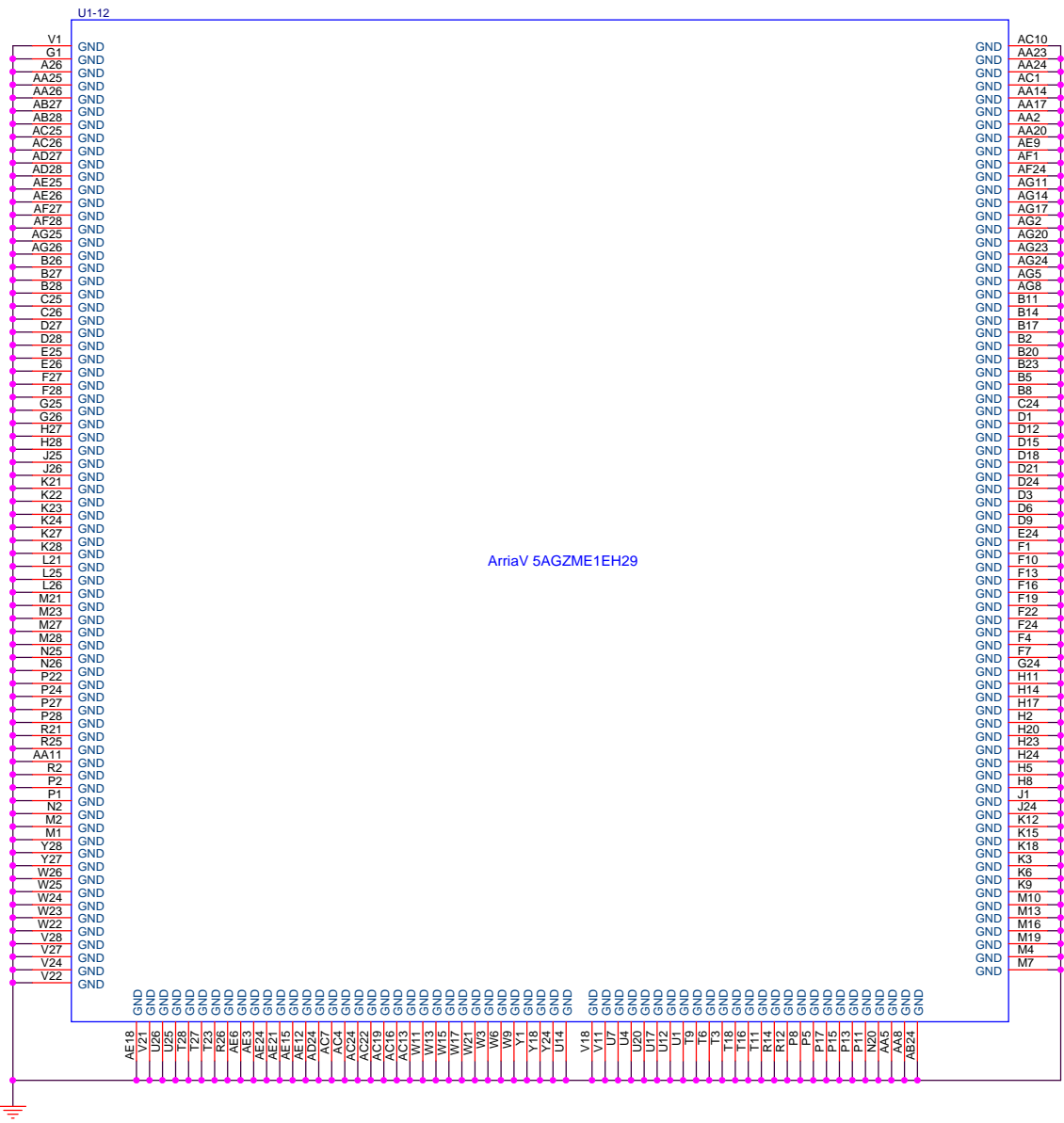
HIGH SPEED BANK

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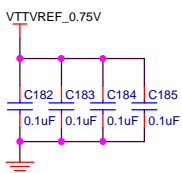
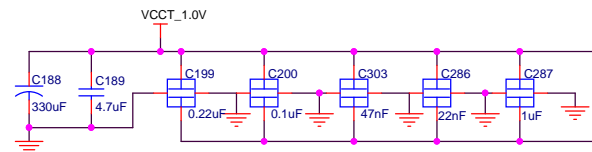
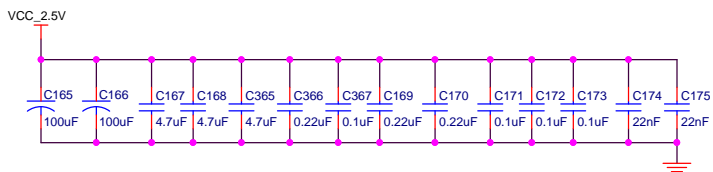
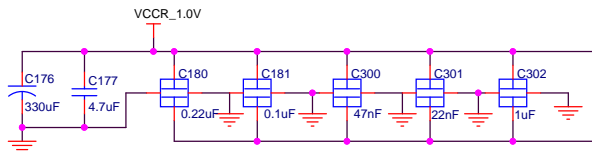
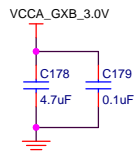
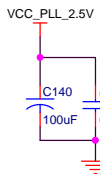
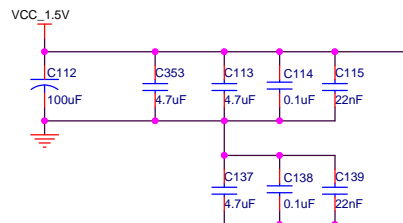
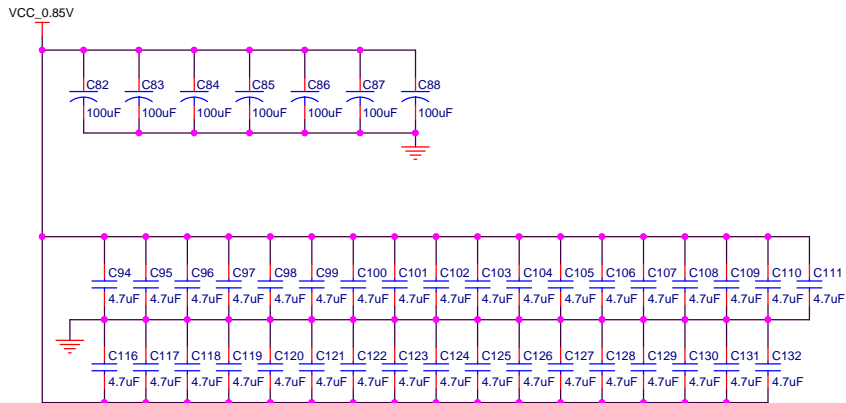


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FPGA GROUND



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FPGA Decoupling

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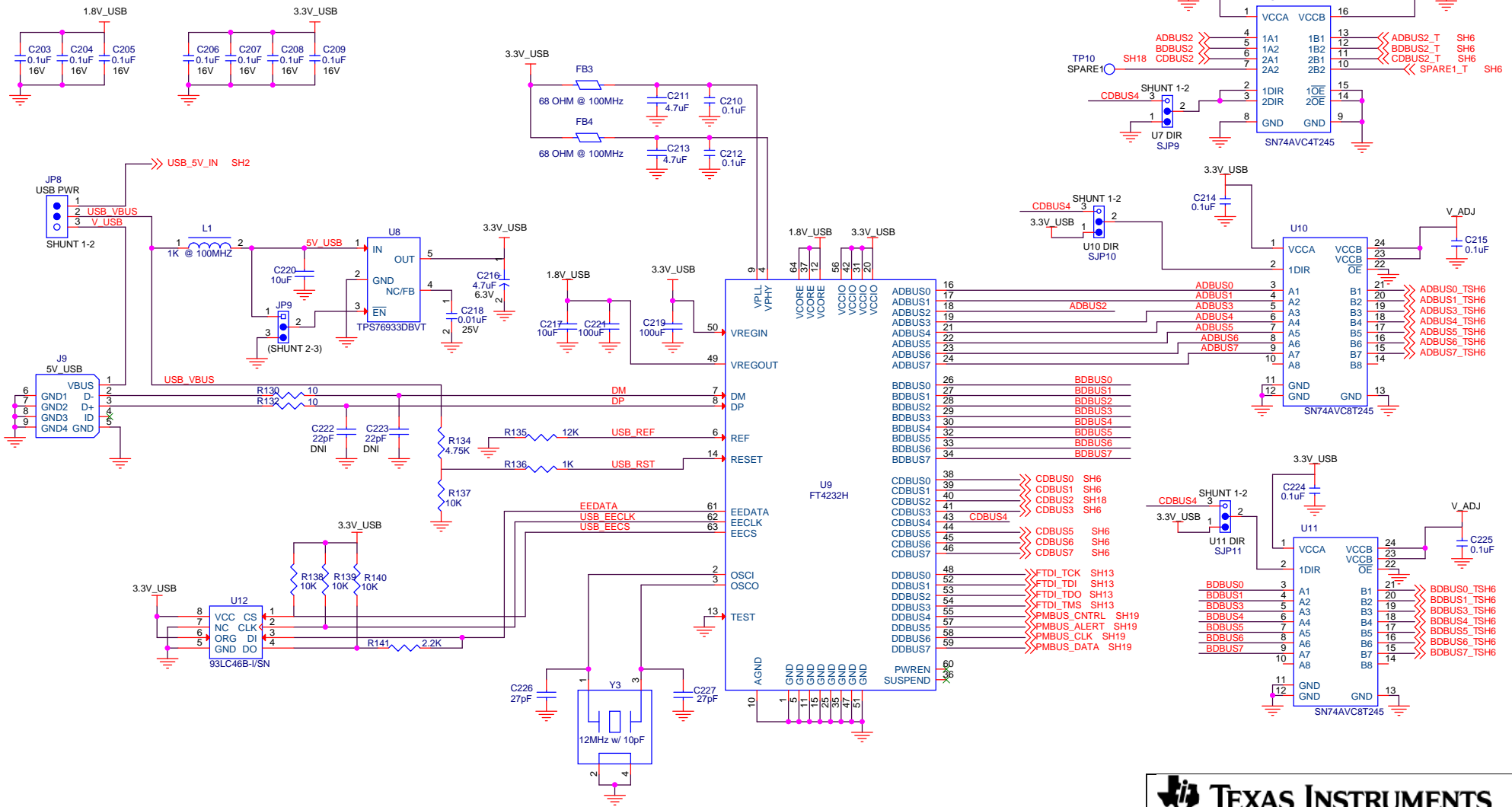
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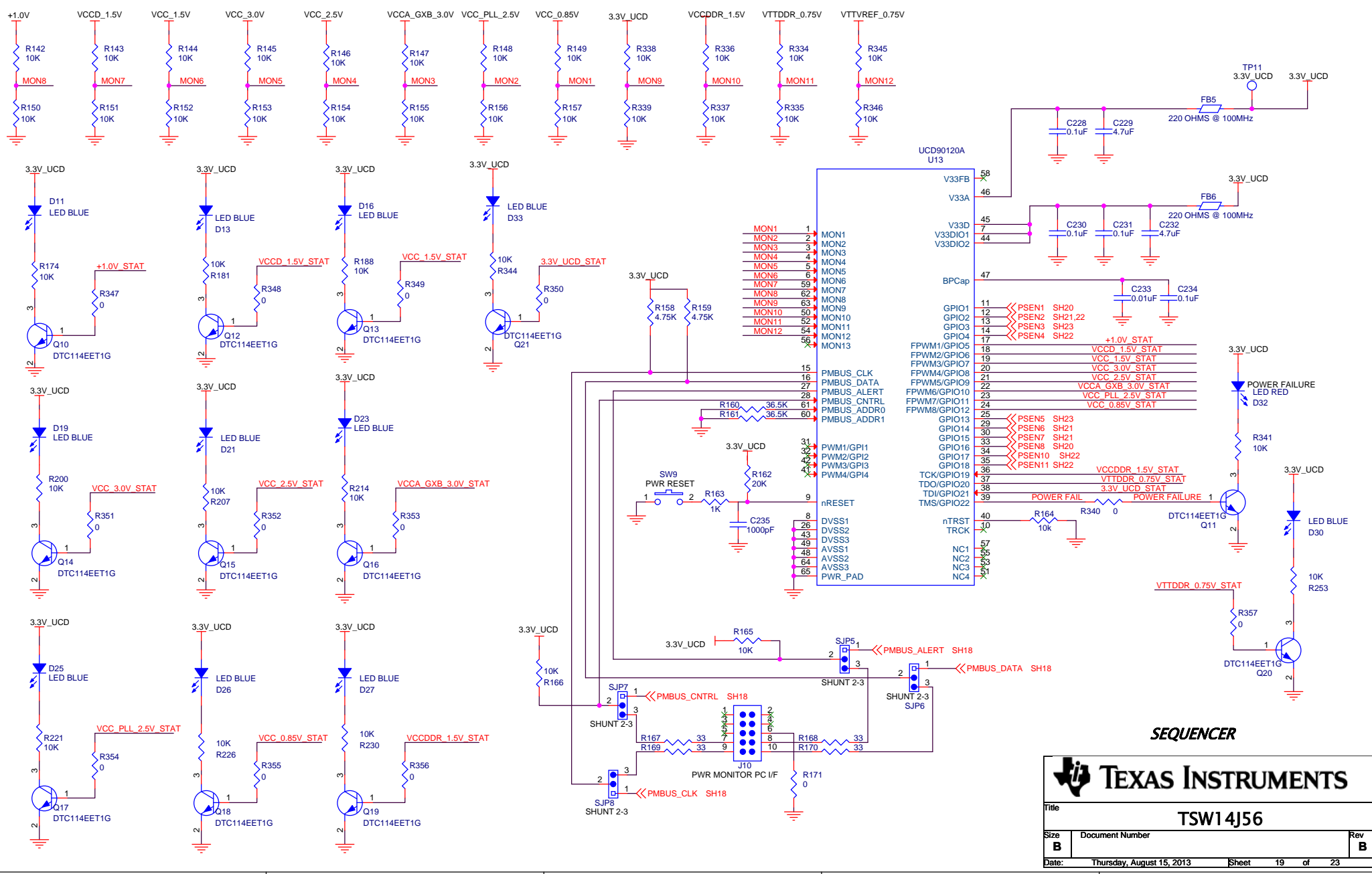
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USB




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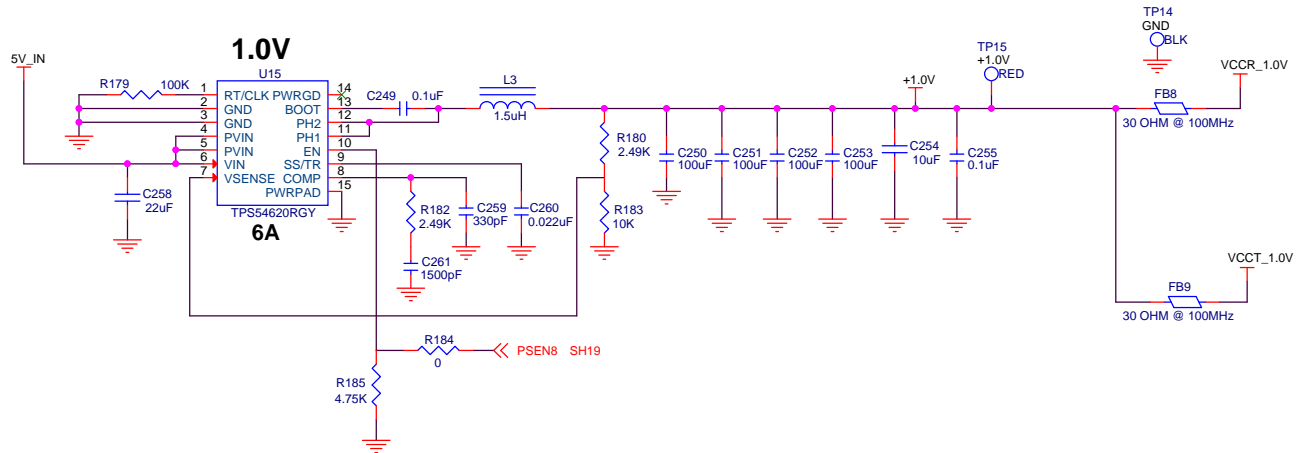
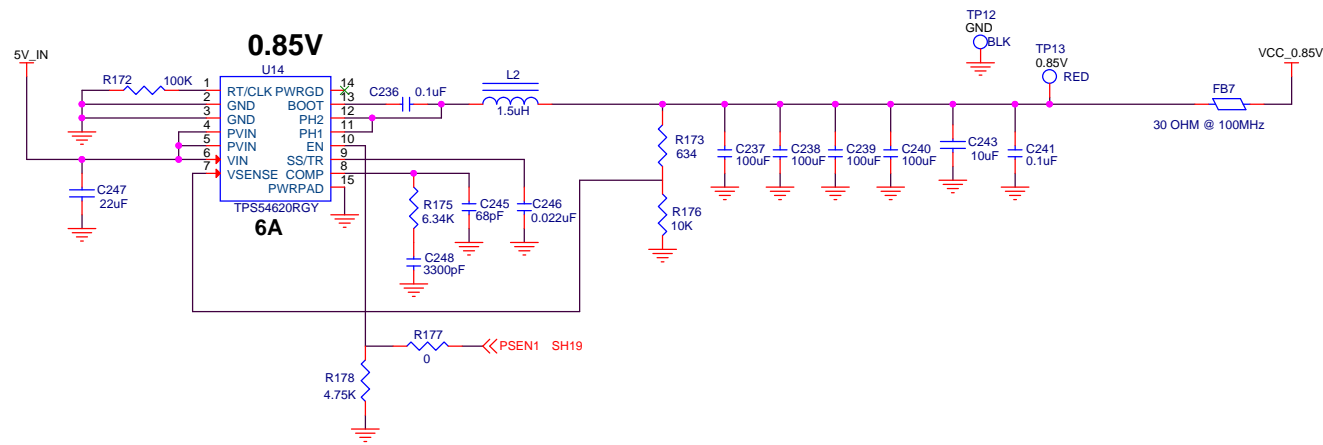
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SEQUENCER

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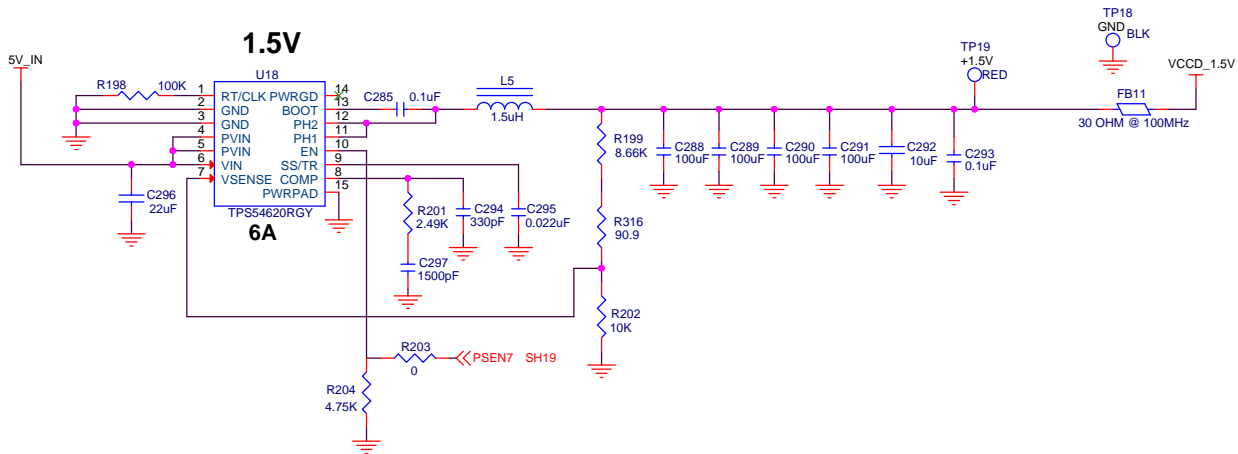
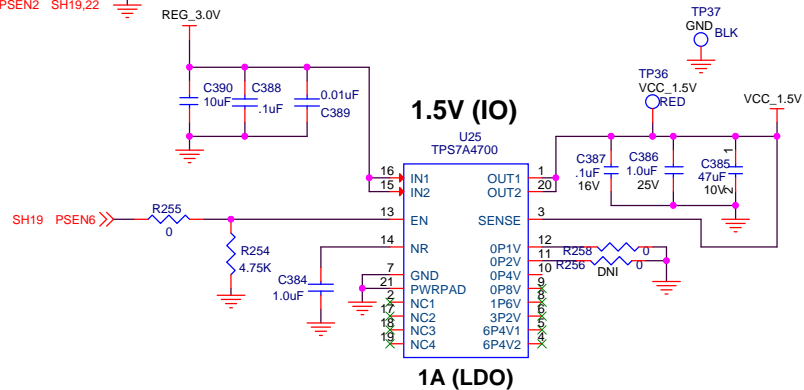
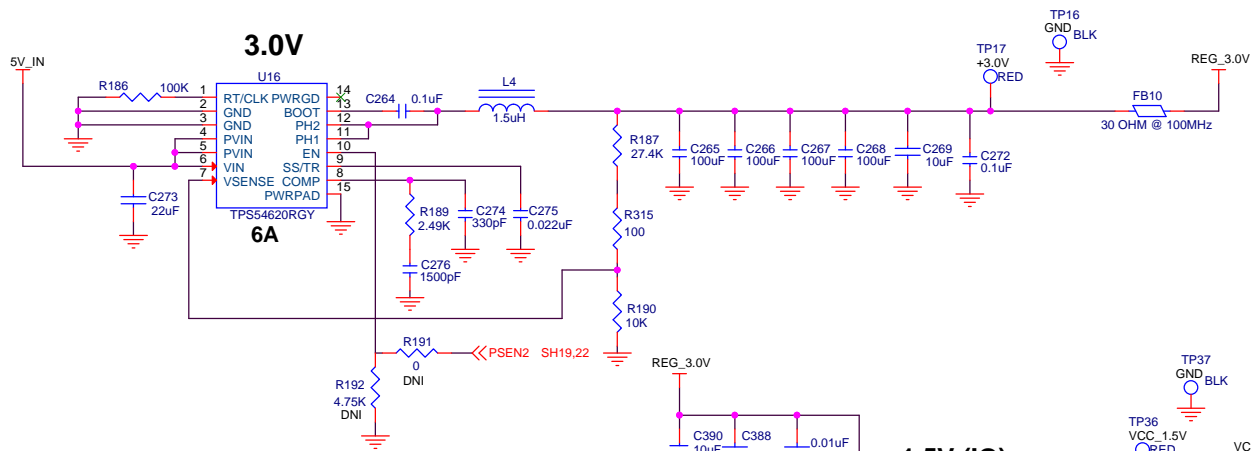
0.85V, 1.0V

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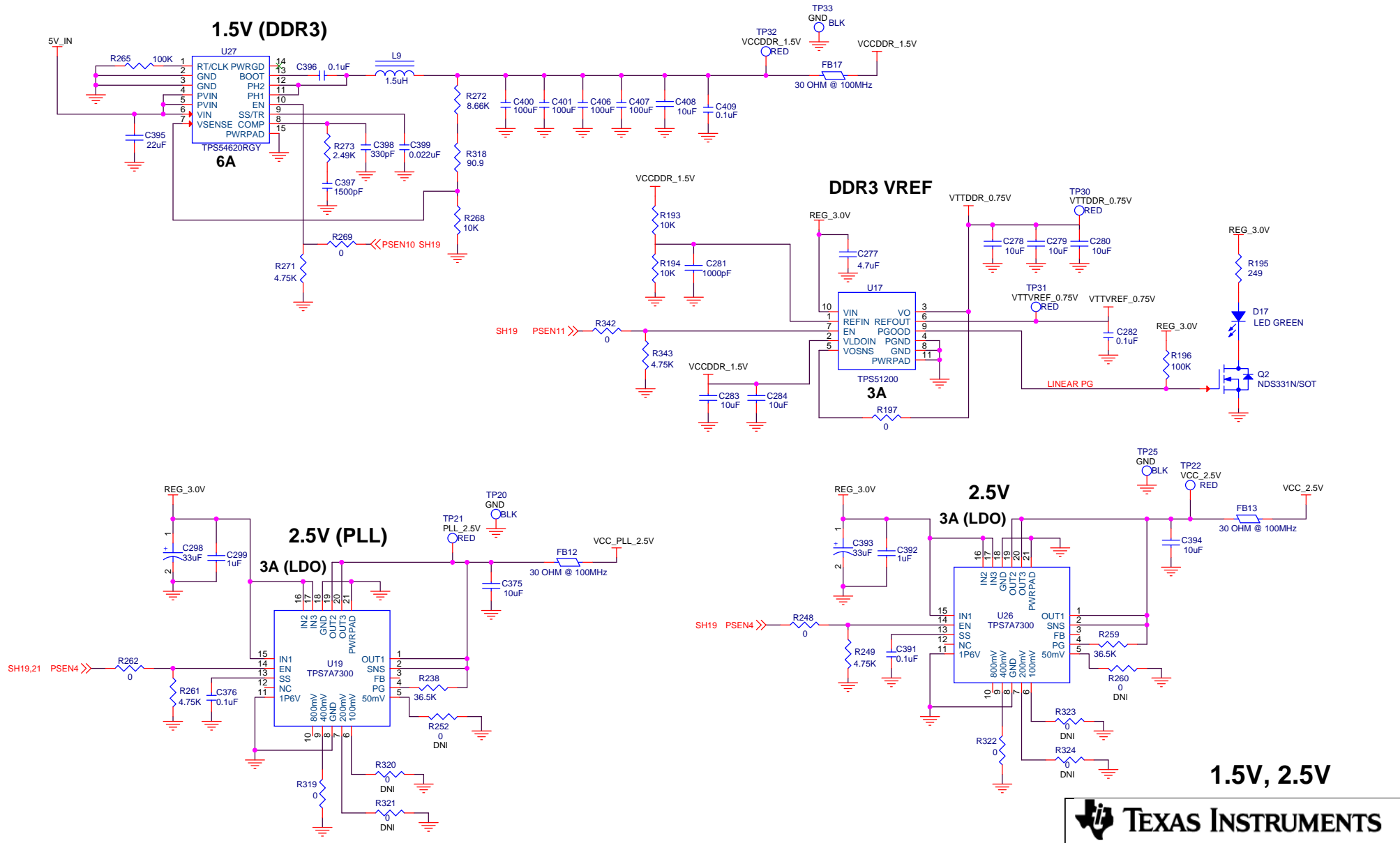
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1.5V



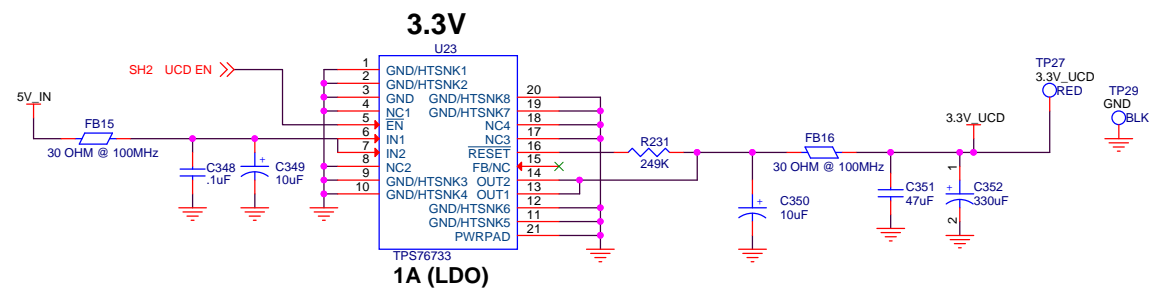
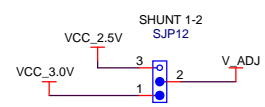
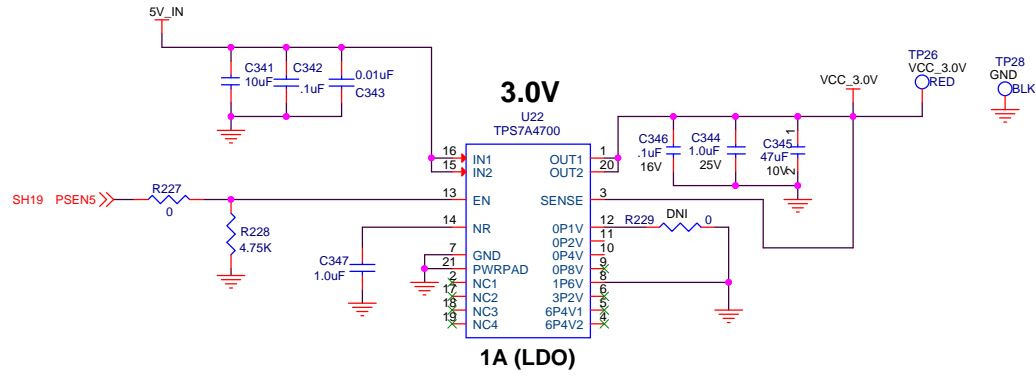
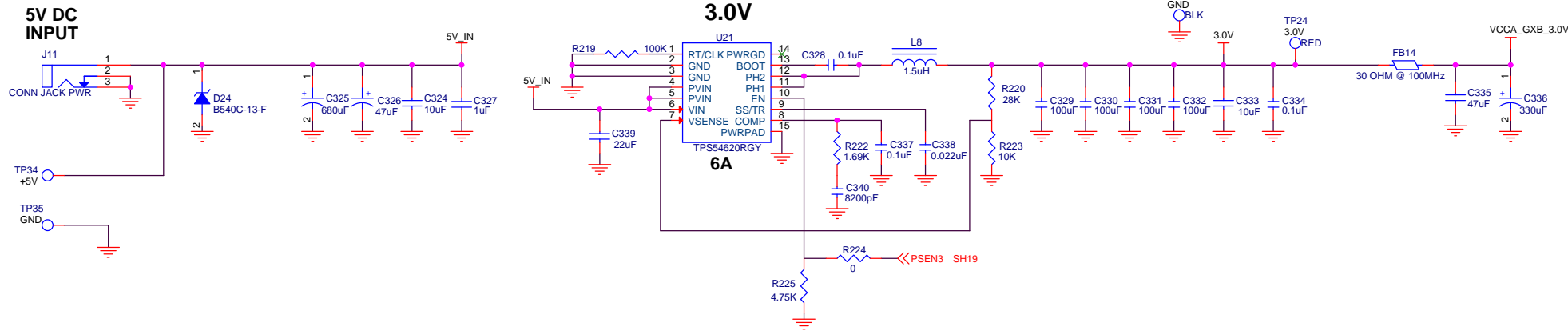
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1.5V, 2.5V



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3.0V, 3.3V

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